

Title (en)  
Polishing apparatus

Title (de)  
Poliervorrichtung

Title (fr)  
Dispositif de polissage

Publication  
**EP 1038635 A2 20000927 (EN)**

Application  
**EP 00302005 A 20000313**

Priority  
US 27064299 A 19990316

Abstract (en)  
A chemical mechanical polishing system having a dual position slurry/rinse arm for moving between a polishing position in which slurry is supplied to a polishing pad from a location remote from the polishing pad's center, and a rinsing position in which rinsing fluid is supplied from a location above or adjacent the polishing pad's center. The rinsing fluid is preferably sprayed from one or more nozzles that extend from the edge of the polishing pad to the center of the polishing pad. Preferably, in the polishing position, the slurry/rinse arm is positioned horizontally remote from the polishing pad's center and supplies slurry to the polishing pad via a horizontally angled slurry supply line. The slurry/rinse arm may include a gimbed brush for contacting the polishing pad when the slurry/rinse arm is in the rinsing position, and may further include brush nozzles positioned to direct rinsing fluid to the brush so as to rinse particles therefrom. Rinsing fluid nozzles may also be angled to spray rinsing fluid in front of the brush, so as to prewet the polishing pad.

IPC 1-7  
**B24B 37/04**; **B24B 53/007**; **H01L 21/306**

IPC 8 full level  
**B24B 37/00** (2006.01); **B24B 37/04** (2006.01); **B24B 53/007** (2006.01); **H01L 21/304** (2006.01)

CPC (source: EP)  
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Cited by  
CN113471108A; WO02076674A3; WO03018256A1

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